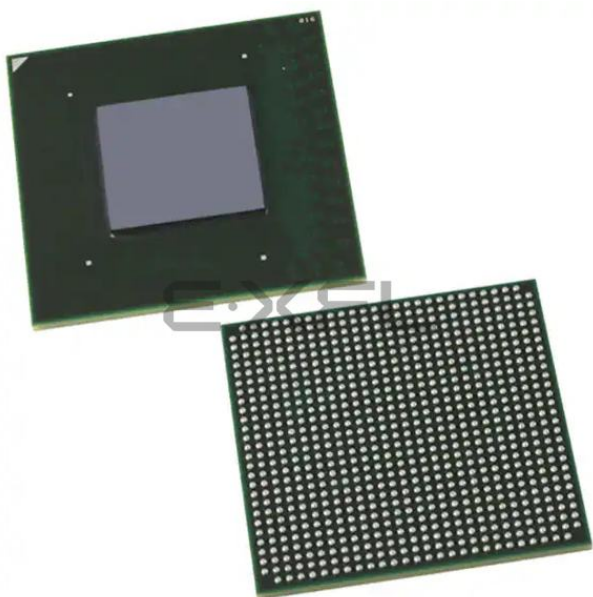




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2530
Number of Logic Elements/Cells	60214
Total RAM Bits	5371904
Number of I/O	364
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx65df29i5n

Table 1–3. Maximum Allowed Overshoot During Transitions for Arria II Devices

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
V_I (AC)	AC Input Voltage	4.0	100.000	%
		4.05	79.330	%
		4.1	46.270	%
		4.15	27.030	%
		4.2	15.800	%
		4.25	9.240	%
		4.3	5.410	%
		4.35	3.160	%
		4.4	1.850	%
		4.45	1.080	%
		4.5	0.630	%
		4.55	0.370	%
		4.6	0.220	%

Maximum Allowed I/O Operating Frequency

Table 1–4 lists the maximum allowed I/O operating frequency for Arria II GX I/Os using the specified I/O standards to ensure device reliability.

Table 1–4. Maximum Allowed I/O Operating Frequency for Arria II GX Devices

I/O Standard	I/O Frequency (MHz)
HSTL-18 and HSTL-15	333
SSTL -15	400
SSTL-18	333
2.5-V LVCMOS	260
3.3-V and 3.0-V LVTTTL	250
3.3-V, 3.0-V, 1.8-V, and 1.5-V LVCMOS	
PCI and PCI-X	
SSTL-2	
1.2-V LVCMOS HSTL-12	200

Table 1–5. Recommended Operating Conditions for Arria II GX Devices (Note 1) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
t_{RAMP}	Power Supply Ramp time	Normal POR	0.05	—	100	ms
		Fast POR	0.05	—	4	ms

Notes to Table 1–5:

- (1) For more information about supply pin connections, refer to the *Arria II Device Family Pin Connection Guidelines*.
- (2) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (3) V_{CCPD} must be 2.5-V for I/O banks with 2.5-V and lower V_{CCIO} , 3.0-V for 3.0-V V_{CCIO} , and 3.3-V for 3.3-V V_{CCIO} .
- (4) V_{CCIO} for 3C and 8C I/O banks where the configuration pins reside only supports 3.3-, 3.0-, 2.5-, or 1.8-V voltage levels.

Table 1–6 lists the recommended operating conditions for Arria II GZ devices.

Table 1–6. Recommended Operating Conditions for Arria II GZ Devices (Note 6) (Part 1 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CC}	Core voltage and periphery circuitry power supply	—	0.87	0.90	0.93	V
V_{CCCB}	Supplies power for the configuration RAM bits	—	1.45	1.50	1.55	V
V_{CCAUX}	Auxiliary supply	—	2.375	2.5	2.625	V
V_{CCPD} (2)	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V_{CCIO}	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V_{CCPGM}	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
$V_{\text{CCA_PLL}}$	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
$V_{\text{CCD_PLL}}$	PLL digital voltage regulator power supply	—	0.87	0.90	0.93	V
$V_{\text{CC_CLKIN}}$	Differential clock input power supply	—	2.375	2.5	2.625	V
V_{CCBAT} (1)	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.3	V
V_{I}	DC input voltage	—	–0.5	—	3.6	V
V_{O}	Output voltage	—	0	—	V_{CCIO}	V
$V_{\text{CCA_L}}$	Transceiver high voltage power (left side)	—	2.85/2.375	3.0/2.5 (4)	3.15/2.625	V
$V_{\text{CCA_R}}$	Transceiver high voltage power (right side)					
$V_{\text{CCHIP_L}}$	Transceiver HIP digital power (left side)	—	0.87	0.9	0.93	V
$V_{\text{CCR_L}}$	Receiver power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCR_R}}$	Receiver power (right side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_L}}$	Transmitter power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_R}}$	Transmitter power (right side)	—	1.05	1.1	1.15	V

Use the following with Equation 1-1:

- R_{SCAL} is the OCT resistance value at power up.
- ΔT is the variation of temperature with respect to the temperature at power up.
- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

Table 1-14 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GX devices.

Table 1-14. OCT Variation after Power-up Calibration for Arria II GX Devices

Nominal Voltage V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.262	0.035
2.5	0.234	0.039
1.8	0.219	0.086
1.5	0.199	0.136
1.2	0.161	0.288

Table 1-15 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GZ devices.

Table 1-15. OCT Variation after Power-Up Calibration for Arria II GZ Devices (Note 1)

Nominal Voltage, V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.189	0.0297
2.5	0.208	0.0344
1.8	0.266	0.0499
1.5	0.273	0.0744
1.2	0.317	0.1241

Note to Table 1-15:

(1) Valid for V_{CCIO} range of $\pm 5\%$ and temperature range of 0° to 85°C.

Pin Capacitance

Table 1-16 lists the pin capacitance for Arria II GX devices.

Table 1-16. Pin Capacitance for Arria II GX Devices

Symbol	Description	Typical	Unit
C_{IO}	Input capacitance on I/O pins, dual-purpose pins (differential I/O, clock, R_{up} , R_{dn}), and dedicated clock input pins	7	pF

Table 1-19 lists the weak pull-up resistor values for Arria II GZ devices.

Table 1-19. Internal Weak Pull-Up Resistor for Arria II GZ Devices (Note 1), (2)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	$V_{CCIO} = 3.0\text{ V} \pm 5\%$ (3)	—	25	—	$k\Omega$
		$V_{CCIO} = 2.5\text{ V} \pm 5\%$ (3)	—	25	—	$k\Omega$
		$V_{CCIO} = 1.8\text{ V} \pm 5\%$ (3)	—	25	—	$k\Omega$
		$V_{CCIO} = 1.5\text{ V} \pm 5\%$ (3)	—	25	—	$k\Omega$
		$V_{CCIO} = 1.2\text{ V} \pm 5\%$ (3)	—	25	—	$k\Omega$

Notes to Table 1-19:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately $25\text{ k}\Omega$.
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .

Hot Socketing

Table 1-20 lists the hot-socketing specification for Arria II GX and GZ devices.

Table 1-20. Hot Socketing Specifications for Arria II Devices

Symbol	Description	Maximum
$I_{IOPIN(DC)}$	DC current per I/O pin	$300\text{ }\mu\text{A}$
$I_{IOPIN(AC)}$	AC current per I/O pin	8 mA (1)
$I_{XCVR TX(DC)}$	DC current per transceiver TX pin	100 mA
$I_{XCVR RX(DC)}$	DC current per transceiver RX pin	50 mA

Note to Table 1-20:

- (1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns , $|I_{IOPIN}| = C\text{ dv/dt}$, in which “C” is I/O pin capacitance and “dv/dt” is slew rate.

Schmitt Trigger Input

The Arria II GX device supports Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rates.

Table 1-21 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Arria II GX devices.

Table 1-21. Schmitt Trigger Input Hysteresis Specifications for Arria II GX Devices

Symbol	Description	Condition (V)	Minimum	Unit
$V_{Schmitt}$	Hysteresis for Schmitt trigger input	$V_{CCIO} = 3.3$	220	mV
		$V_{CCIO} = 2.5$	180	mV
		$V_{CCIO} = 1.8$	110	mV
		$V_{CCIO} = 1.5$	70	mV

Table 1-26 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GX devices.

Table 1-26. Single-Ended SSTL and HSTL I/O Standard Signal Specifications for Arria II GX Devices

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.4	-16.4
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
HSTL-18 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	14	-14

Table 1-27 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GZ devices.

Table 1-27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 1 of 2)

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8

Table 1–33 lists the differential I/O standard specifications for Arria II GZ devices.

Table 1–33. Differential I/O Standard Specifications for Arria II GZ Devices (Note 1)

I/O Standard (2)	V _{CCIO} (V)			V _{ID} (mV)			V _{ICM(DC)} (V)		V _{OD} (V) (3)			V _{OCM} (V) (3)		
	Min	Typ	Max	Min	Cond.	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
2.5 V LVDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1.125	1.25	1.375
2.5 V LVDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1	1.25	1.5
RSDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.4
RSDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.5
Mini-LVDS (HIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.4
Mini-LVDS (VIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.5
LVPECL	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
BLVDS (4)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—

Notes to Table 1–33:

- (1) 1.4-V/1.5-V PCML transceiver I/O standard specifications are described in “Transceiver Performance Specifications” on page 1–21.
- (2) Vertical I/O (VIO) is top and bottom I/Os; horizontal I/O (HIO) is left and right I/Os.
- (3) R_L range: 90 ≤ R_L ≤ 110 Ω.
- (4) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. These specifications depend on the system topology.

Power Consumption for the Arria II Device Family

Altera offers two ways to estimate power for a design:

- Using the Microsoft Excel-based Early Power Estimator
- Using the Quartus® II PowerPlay Power Analyzer feature

The interactive Microsoft Excel-based Early Power Estimator is typically used prior to designing the FPGA in order to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities which, when combined with detailed circuit models, can yield very accurate power estimates.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Switching Characteristics

This section provides performance characteristics of the Arria II GX and GZ core and periphery blocks for commercial grade devices. The following tables are considered final and are based on actual silicon characterization and testing. These numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions.

Transceiver Performance Specifications

Table 1–34 lists the Arria II GX transceiver specifications.

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 1 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock														
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL													
Input frequency from REFCLK input pins	—	50	—	622.08	50	—	622.08	50	—	622.08	50	—	622.08	MHz
Input frequency from PLD input	—	50	—	200	50	—	200	50	—	200	50	—	200	MHz
Absolute V _{MAX} for a REFCLK pin	—	—	—	2.2	—	—	2.2	—	—	2.2	—	—	2.2	V
Absolute V _{MIN} for a REFCLK pin	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	V
Rise/fall time (2)	—	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	2000	200	—	2000	200	—	2000	200	—	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	30	—	33	30	—	33	kHz

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 2 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	—	100	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	$1100 \pm 5\%$			$1100 \pm 5\%$			$1100 \pm 5\%$			$1100 \pm 5\%$			mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	≥ 1 MHz	—	—	-130	—	—	-130	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK (3)	10 KHz to 20 MHz	—	—	3	—	—	3	—	—	3	—	—	3	ps
R_{ref}	—	—	$2000 \pm 1\%$	—	—	$2000 \pm 1\%$	—	—	$2000 \pm 1\%$	—	—	$2000 \pm 1\%$	—	Ω
Transceiver Clocks														
Calibration block clock frequency (cal_blk_clk)	—	10	—	125	10	—	125	10	—	125	10	—	125	MHz

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 6 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Intra-differential pair skew	—	—	—	15	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block skew	PCIe ×4	—	—	120	—	—	120	—	—	120	—	—	120	ps
Inter-transceiver block skew	PCIe ×8	—	—	300	—	—	300	—	—	300	—	—	300	ps
CMU PLL0 and CMU PLL1														
CMU PLL lock time from CMUPLL_reset deassertion	—	—	—	100	—	—	100	—	—	100	—	—	100	μs
PLD-Transceiver Interface														
Interface speed	—	25	—	320	25	—	240	25	—	240	25	—	200	MHz

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 7 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Digital reset pulse width	—	Minimum is 2 parallel clock cycles												

Notes to Table 1–34:

- (1) For AC-coupled links, the on-chip biasing circuit is switched off before and during configuration. Ensure that input specifications are not violated during this period.
- (2) The rise/fall time is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode. For more information, refer to [AN 558: Implementing Dynamic Reconfiguration in Arria II Devices](#).
- (5) If your design uses more than one dynamic reconfiguration controller instances (`altgx_reconfig`) to control the transceiver channels (`altgx`) physically located on the same side of the device, and if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS and the link is DC-coupled.
- (8) The rate matcher supports only up to ± 300 parts per million (ppm).
- (9) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to [Figure 1–1](#).
- (10) The time in which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to [Figure 1–1](#).
- (11) The time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to [Figure 1–1](#).
- (12) The time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to [Figure 1–2](#).
- (13) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 5 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
-3 dB Bandwidth	PCIe Gen1	2.5 - 3.5						MHz
	PCIe Gen2	6 - 8						MHz
	(OIF) CEI PHY at 4.976 Gbps	7 - 11						MHz
	(OIF) CEI PHY at 6.375 Gbps	5 - 10						MHz
	XAUI	2 - 4						MHz
	SRIO 1.25 Gbps	3 - 5.5						MHz
	SRIO 2.5 Gbps	3 - 5.5						MHz
	SRIO 3.125 Gbps	2 - 4						MHz
	GIGE	2.5 - 4.5						MHz
	SONET OC12	1.5 - 2.5						MHz
	SONET OC48	3.5 - 6						MHz
Transceiver-FPGA Fabric Interface								
Interface speed	—	25	—	325	25	—	250	MHz
Digital reset pulse width	—	Minimum is two parallel clock cycles						—

Notes to Table 1–35:

- (1) The 3x speed grade is the fastest speed grade offered in the following Arria II GZ devices: EP2AGZ225, EP2AGZ300, and EP2AGZ350.
- (2) The rise and fall time transition is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode.
- (5) If your design uses more than one dynamic reconfiguration controller (`altgx_reconfig`) instances to control the transceiver (`altgx`) channels physically located on the same side of the device AND if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS.
- (8) The differential eye opening specification at the receiver input pins assumes that Receiver Equalization is disabled. If you enable Receiver Equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level. Use H-Spice simulation to derive the minimum eye opening requirement with Receiver Equalization enabled.
- (9) The rate matcher supports only up to ± 300 ppm.
- (10) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to [Figure 1–1 on page 1–33](#).
- (11) Time for which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to [Figure 1–1 on page 1–33](#).
- (12) Time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to [Figure 1–1 on page 1–33](#).
- (13) Time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to [Figure 1–2 on page 1–33](#).
- (14) A GPLL may be required to meet the PMA-FPGA fabric interface timing above certain data rates. For more information, refer to the [Transceiver Clocking for Arria II Devices](#) chapter.
- (15) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (16) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Figure 1-1 shows the lock time parameters in manual mode.

 LTD = lock-to-data. LTR = lock-to-reference.

Figure 1-1. Lock Time Parameters for Manual Mode

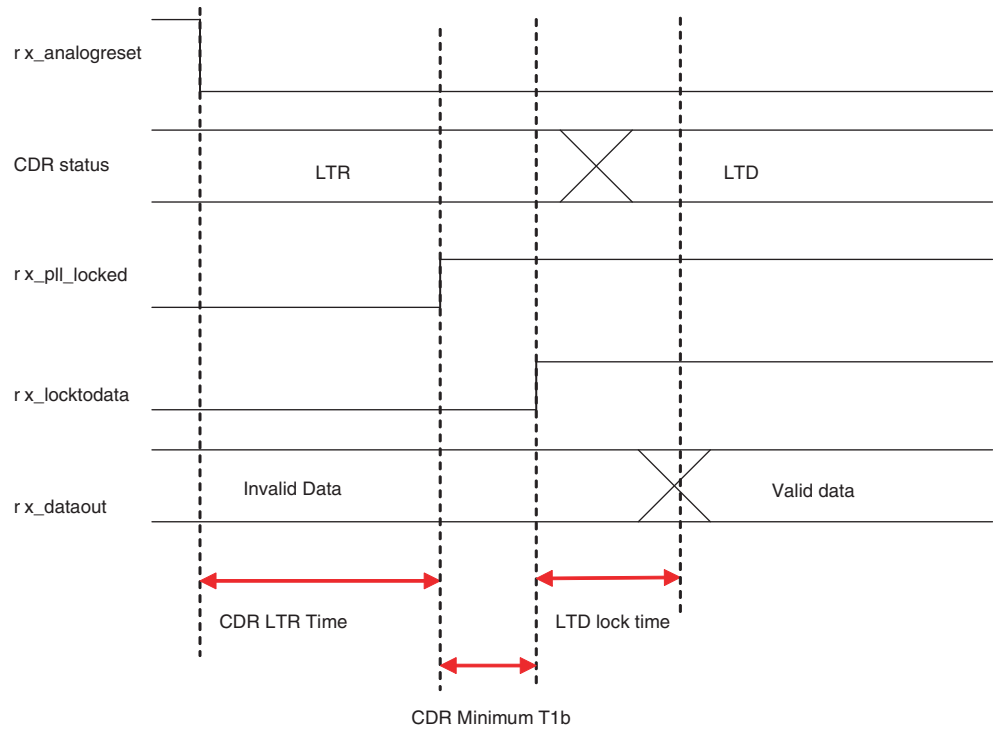


Figure 1-2 shows the lock time parameters in automatic mode.

Figure 1-2. Lock Time Parameters for Automatic Mode

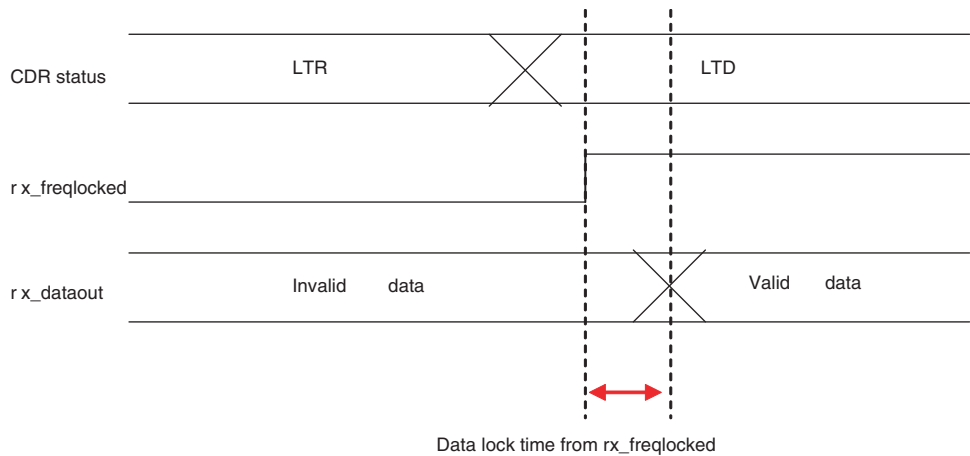


Figure 1-3 shows the differential receiver input waveform.

Figure 1-3. Receiver Input Waveform

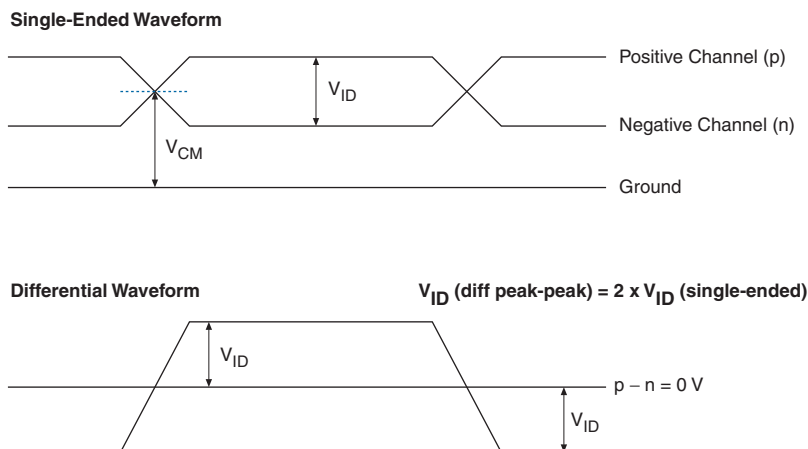


Figure 1-4 shows the transmitter output waveform.

Figure 1-4. Transmitter Output Waveform

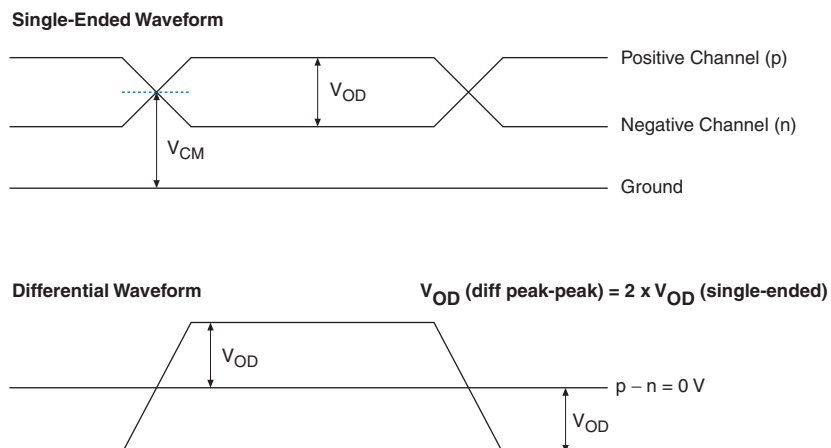


Table 1-36 lists the typical V_{OD} for TX term that equals $85\ \Omega$ for Arria II GZ devices.

Table 1-36. Typical V_{OD} Setting, TX Term = $85\ \Omega$ for Arria II GZ Devices

Symbol	V_{OD} Setting (mV)							
	0	1	2	3	4	5	6	7
V_{OD} differential peak-to-peak Typical (mV)	$170 \pm 20\%$	$340 \pm 20\%$	$510 \pm 20\%$	$595 \pm 20\%$	$680 \pm 20\%$	$765 \pm 20\%$	$850 \pm 20\%$	$1020 \pm 20\%$

Table 1–44. PLL Specifications for Arria II GX Devices (Part 2 of 3)

Symbol	Description	Min	Typ	Max	Unit
f_{OUT}	Output frequency for internal global or regional clock (–4 Speed Grade)	—	—	500	MHz
	Output frequency for internal global or regional clock (–5 Speed Grade)	—	—	500	MHz
	Output frequency for internal global or regional clock (–6 Speed Grade)	—	—	400	MHz
f_{OUT_EXT}	Output frequency for external clock output (–4 Speed Grade)	—	—	670 (5)	MHz
	Output frequency for external clock output (–5 Speed Grade)	—	—	622 (5)	MHz
	Output frequency for external clock output (–6 Speed Grade)	—	—	500 (5)	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	45	50	55	%
t_{OUTPJ_DC}	Dedicated clock output period jitter ($f_{OUT} \geq 100$ MHz)	—	—	300	ps (p–p)
	Dedicated clock output period jitter ($f_{OUT} < 100$ MHz)	—	—	30	mUI (p–p)
t_{OUTCCJ_DC}	Dedicated clock output cycle-to-cycle jitter ($f_{OUT} \geq 100$ MHz)	—	—	300	ps (p–p)
	Dedicated clock output cycle-to-cycle jitter ($f_{OUT} < 100$ MHz)	—	—	30	mUI (p–p)
f_{OUTPJ_IO}	Regular I/O clock output period jitter ($f_{OUT} \geq 100$ MHz)	—	—	650	ps (p–p)
	Regular I/O clock output period jitter ($f_{OUT} < 100$ MHz)	—	—	65	mUI (p–p)
f_{OUTCCJ_IO}	Regular I/O clock output cycle-to-cycle jitter ($f_{OUT} \geq 100$ MHz)	—	—	650	ps (p–p)
	Regular I/O clock output cycle-to-cycle jitter ($f_{OUT} < 100$ MHz)	—	—	65	mUI (p–p)
$t_{CONFIGPLL}$	Time required to reconfigure PLL scan chains	—	3.5	—	SCANCLK cycles
$t_{CONFIGPHASE}$	Time required to reconfigure phase shift	—	1	—	SCANCLK cycles
$f_{SCANCLK}$	SCANCLK frequency	—	—	100	MHz
t_{LOCK}	Time required to lock from end of device configuration	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
$f_{CL\ BW}$	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on areset signal	10	—	—	ns

DSP Block Specifications

Table 1-46 lists the DSP block performance specifications for Arria II GX devices.

Table 1-46. DSP Block Performance Specifications for Arria II GX Devices (Note 1)

Mode	Resources Used	Performance				Unit
	Number of Multipliers	C4	I3	C5,I5	C6	
9 × 9-bit multiplier	1	380	310	300	250	MHz
12 × 12-bit multiplier	1	380	310	300	250	MHz
18 × 18-bit multiplier	1	380	310	300	250	MHz
36 × 36-bit multiplier	1	350	270	270	220	MHz
18 × 36-bit high-precision multiplier adder mode	1	350	270	270	220	MHz
18 × 18-bit multiply accumulator	4	380	310	300	250	MHz
18 × 18-bit multiply adder	4	380	310	300	250	MHz
18 × 18-bit multiply adder-signed full precision	2	380	310	300	250	MHz
18 × 18-bit multiply adder with loopback (2)	2	275	220	220	180	MHz
36-bit shift (32-bit data)	1	350	270	270	220	MHz
Double mode	1	350	270	270	220	MHz

Notes to Table 1-46:

- (1) Maximum is for a fully-pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum is for loopback input registers disabled, **Round** and **Saturation** disabled, pipeline and output registers enabled.

Table 1-47 lists the DSP block performance specifications for Arria II GZ devices.

Table 1-47. DSP Block Performance Specifications for Arria II GZ Devices (Note 1) (Part 1 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	-3	-4	
9 × 9-bit multiplier	1	460	400	MHz
12 × 12-bit multiplier	1	500	440	MHz
18 × 18-bit multiplier	1	550	480	MHz
36 × 36-bit multiplier	1	440	380	MHz
18 × 18-bit multiply accumulator	4	440	380	MHz
18 × 18-bit multiply adder	4	470	410	MHz
18 × 18-bit multiply adder-signed full precision	2	450	390	MHz
18 × 18-bit multiply adder with loopback (2)	2	350	310	MHz
36-bit shift (32-bit data)	1	440	380	MHz

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - f_{HSDRPA} (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1–53. High-Speed I/O Specifications for Arria II GX Devices (Part 4 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(3)	945 (7)	(3)	945 (7)	(3)	740 (7)	(3)	640 (7)	Mbps
	SERDES factor J = 2 (using DDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
	SERDES factor J = 1 (using SDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
Soft-CDR PPM tolerance	Soft-CDR mode	—	300	—	300	—	300	—	300	±PPM
DPA run length	DPA mode	—	10,000	—	10,000	—	10,000	—	10,000	UI
Sampling window (SW)	Non-DPA mode (5)	—	300	—	300	—	350	—	400	ps

Notes to Table 1–53:

- (1) $f_{\text{HCLK_IN}} = f_{\text{HSDR}} / W$. Use W to determine the supported selection of input reference clock frequencies for the desired data rate.
- (2) Applicable for interfacing with DPA receivers only. For interfacing with non-DPA receivers, you must calculate the leftover timing margin in the receiver by performing link timing closure analysis. For Arria II GX transmitter to Arria II GX non-DPA receiver, the maximum supported data rate is 945 Mbps. For data rates above 840 Mbps, perform PCB trace compensation by adjusting the PCB trace length for LVDS channels to improve channel-to-channel skews.
- (3) The minimum and maximum specification depends on the clock source (for example, PLL and clock pin) and the clock routing resource you use (global, regional, or local). The I/O differential buffer and input register do not have a minimum toggle rate.
- (4) The specification is only applicable under the influence of core noise.
- (5) Applicable for true LVDS using dedicated SERDES only.
- (6) Dedicated SERDES and DPA features are only available on the right banks.
- (7) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and the receiver sampling margin to determine the leftover timing margin.

Table 1–54 lists the high-speed I/O timing for Arria II GZ devices.

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 1 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Clock								
f _{HCLK_in} (input clock frequency) true differential I/O standards	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f _{HCLK_in} (input clock frequency) single ended I/O standards (9)	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f _{HCLK_in} (input clock frequency) single ended I/O standards (10)	Clock boost factor W = 1 to 40 (3)	5	—	420	5	—	420	MHz

Table 1-57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1-57:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1-58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1-58. DLL Frequency Range Specifications for Arria II GZ Devices

Frequency Mode	Frequency Range (MHz)		Available Phase Shift	DQS Delay Buffer Mode (1)	Number of Delay Chains
	-3	-4			
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°, 135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1-58:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1-59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1-59. DQS Phase Offset Delay Per Setting for Arria II GX Devices (Note 1), (2), (3)

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1-59:

- (1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.
- (2) The typical value equals the average of the minimum and maximum values.
- (3) The delay settings are linear.

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	- Updated the $V_{CCH_GXBL/R}$ operating conditions in Table 1–6. - Finalized Arria II GZ information in Table 1–20. - Added BLVDS specification in Table 1–32 and Table 1–33. - Updated input and output waveforms in Table 1–68.
December 2011	4.2	- Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. - Minor text edits.
June 2011	4.1	- Added Table 1–60. - Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. - Updated the “Switching Characteristics” section introduction. - Minor text edits.

Table 1-69. Document Revision History (Part 2 of 2)

Date	Version	Changes
December 2010	4.0	■ Added Arria II GZ information. ■ Added Table 1-61 with Arria II GX information. ■ Updated Table 1-1, Table 1-2, Table 1-5, Table 1-6, Table 1-7, Table 1-11, Table 1-35, Table 1-37, Table 1-40, Table 1-42, Table 1-44, Table 1-45, Table 1-57, Table 1-61, and Table 1-63. ■ Updated Figure 1-5. ■ Updated for the Quartus II version 10.0 release. ■ Updated the first paragraph for searchability. ■ Minor text edits.
July 2010	3.0	■ Updated Table 1-1, Table 1-4, Table 1-16, Table 1-19, Table 1-21, Table 1-23, Table 1-25, Table 1-26, Table 1-30, and Table 1-35 ■ Added Table 1-27 and Table 1-29. ■ Added I3 speed grade information to Table 1-19, Table 1-21, Table 1-22, Table 1-24, Table 1-25, Table 1-30, Table 1-32, Table 1-33, Table 1-34, and Table 1-35. ■ Updated the “Operating Conditions” section. ■ Removed “Preliminary” from Table 1-19, Table 1-21, Table 1-22, Table 1-23, Table 1-24, Table 1-25, Table 1-26, Table 1-28, Table 1-30, Table 1-32, Table 1-33, Table 1-34, and Figure 1-4. ■ Minor text edits.
March 2010	2.3	Updated for the Quartus II version 9.1 SP2 release: ■ Updated Table 1-3, Table 1-7, Table 1-19, Table 1-21, Table 1-22, Table 1-24, Table 1-25 and Table 1-33. ■ Updated “Recommended Operating Conditions” section. ■ Minor text edits.
February 2010	2.2	Updated Table 1-19.
February 2010	2.1	Updated for Arria II GX v9.1 SP1 release: ■ Updated Table 1-19, Table 1-23, Table 1-28, Table 1-30, and Table 1-33. ■ Added Figure 1-5. ■ Minor text edits.
November 2009	2.0	Updated for Arria II GX v9.1 release: ■ Updated Table 1-1, Table 1-4, Table 1-13, Table 1-14, Table 1-19, Table 1-15, Table 1-22, Table 1-24, and Table 1-28. ■ Added Table 1-6 and Table 1-33. ■ Added “Bus Hold” on page 1-5. ■ Added “IOE Programmable Delay” section. ■ Minor text edit.
June 2009	1.2	■ Updated Table 1-1, Table 1-3, Table 1-7, Table 1-8, Table 1-18, Table 1-23, Table 1-25, Table 1-26, Table 1-29, Table 1-30, Table 1-31, Table 1-32, and Table 1-33. ■ Added Table 1-32. ■ Updated Equation 1-1.
March 2009	1.1	Added “I/O Timing” section.
February 2009	1.0	Initial release.